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### **Understanding Embedded - FPGAs (Field Programmable Gate Array)**

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

### **Applications of Embedded - FPGAs**

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

#### **Details**

Product Status	Active
Number of LABs/CLBs	2880
Number of Logic Elements/Cells	-
Total RAM Bits	-
Number of I/O	203
Number of Gates	48000
Voltage - Supply	2.25V ~ 5.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 70°C (TA)
Package / Case	256-LBGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/microchip-technology/a54sx32a-fgg256">https://www.e-xfl.com/product-detail/microchip-technology/a54sx32a-fgg256</a>

## Logic Module Design

The SX-A family architecture is described as a “sea-of-modules” architecture because the entire floor of the device is covered with a grid of logic modules with virtually no chip area lost to interconnect elements or routing. The Actel SX-A family provides two types of logic modules: the register cell (R-cell) and the combinatorial cell (C-cell).

The R-cell contains a flip-flop featuring asynchronous clear, asynchronous preset, and clock enable, using the S0 and S1 lines control signals (Figure 1-2). The R-cell registers feature programmable clock polarity selectable on a register-by-register basis. This provides additional flexibility while allowing mapping of synthesized functions into the SX-A FPGA. The clock source for the R-cell can be chosen from either the hardwired clock, the routed clocks, or internal logic.

The C-cell implements a range of combinatorial functions of up to five inputs (Figure 1-3). Inclusion of the DB input and its associated inverter function allows up to 4,000

different combinatorial functions to be implemented in a single module. An example of the flexibility enabled by the inversion capability is the ability to integrate a 3-input exclusive-OR function into a single C-cell. This facilitates construction of 9-bit parity-tree functions with 1.9 ns propagation delays.

## Module Organization

All C-cell and R-cell logic modules are arranged into horizontal banks called Clusters. There are two types of Clusters: Type 1 contains two C-cells and one R-cell, while Type 2 contains one C-cell and two R-cells.

Clusters are grouped together into SuperClusters (Figure 1-4 on page 1-3). SuperCluster 1 is a two-wide grouping of Type 1 Clusters. SuperCluster 2 is a two-wide group containing one Type 1 Cluster and one Type 2 Cluster. SX-A devices feature more SuperCluster 1 modules than SuperCluster 2 modules because designers typically require significantly more combinatorial logic than flip-flops.

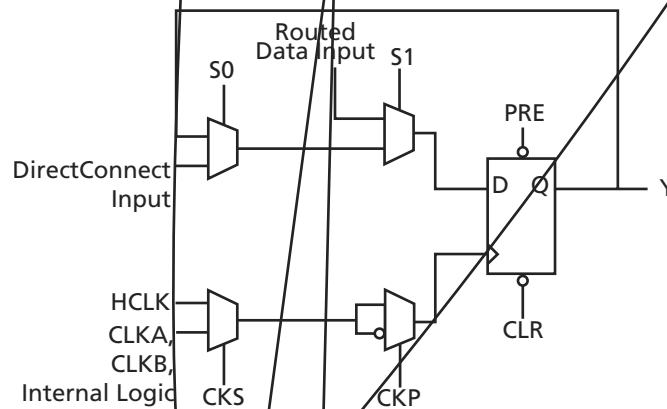


Figure 1-2 • R-Cell

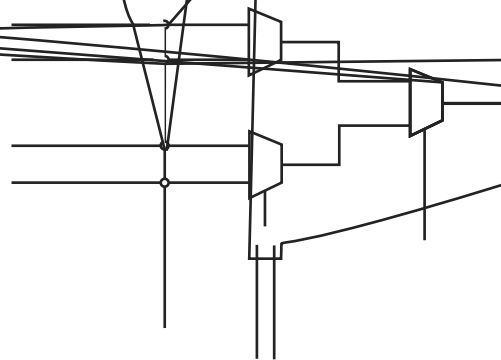


Figure 1-3 • C-Cell

## Other Architectural Features

### Technology

The Actel SX-A family is implemented on a high-voltage, twin-well CMOS process using 0.22  $\mu$  / 0.25  $\mu$  design rules. The metal-to-metal antifuse is comprised of a combination of amorphous silicon and dielectric material with barrier metals and has a programmed ('on' state) resistance of 25  $\Omega$  with capacitance of 1.0 fF for low signal impedance.

### Performance

The unique architectural features of the SX-A family enable the devices to operate with internal clock frequencies of 350 MHz, causing very fast execution of even complex logic functions. The SX-A family is an optimal platform upon which to integrate the functionality previously contained in multiple complex programmable logic devices (CPLDs). In addition, designs that previously would have required a gate array to meet performance goals can be integrated into an SX-A device with dramatic improvements in cost and time-to-market. Using timing-driven place-and-route tools, designers can achieve highly deterministic device performance.

### User Security

Reverse engineering is virtually impossible in SX-A devices because it is extremely difficult to distinguish between programmed and unprogrammed antifuses. In addition, since SX-A is a nonvolatile, single-chip solution, there is no configuration bitstream to intercept at device power-up.

The Actel FuseLock advantage ensures that unauthorized users will not be able to read back the contents of an Actel antifuse FPGA. In addition to the inherent strengths of the architecture, special security fuses that prevent internal probing and overwriting are hidden throughout the fabric of the device. They are located where they cannot be accessed or bypassed without destroying access to the rest of the device, making both invasive and more-subtle noninvasive attacks ineffective against Actel antifuse FPGAs.

Look for this symbol to ensure your valuable IP is secure (Figure 1-11).



Figure 1-11 • FuseLock

For more information, refer to Actel's *Implementation of Security in Actel Antifuse FPGAs* application note.

## I/O Modules

For a simplified I/O schematic, refer to Figure 1 in the application note, *Actel eX, SX-A, and RTSX-S I/Os*.

Each user I/O on an SX-A device can be configured as an input, an output, a tristate output, or a bidirectional pin. Mixed I/O standards can be set for individual pins, though this is only allowed with the same voltage as the input. These I/Os, combined with array registers, can achieve clock-to-output-pad timing as fast as 3.8 ns, even without the dedicated I/O registers. In most FPGAs, I/O cells that have embedded latches and flip-flops, requiring instantiation in HDL code; this is a design complication not encountered in SX-A FPGAs. Fast pin-to-pin timing ensures that the device is able to interface with any other device in the system, which in turn enables parallel design of system components and reduces overall design time. All unused I/Os are configured as tristate outputs by the Actel Designer software, for maximum flexibility when designing new boards or migrating existing designs.

SX-A I/Os should be driven by high-speed push-pull devices with a low-resistance pull-up device when being configured as tristate output buffers. If the I/O is driven by a voltage level greater than  $V_{CC1}$  and a fast push-pull device is NOT used, the high-resistance pull-up of the driver and the internal circuitry of the SX-A I/O may create a voltage divider. This voltage divider could pull the input voltage below specification for some devices connected to the driver. A logic '1' may not be correctly presented in this case. For example, if an open drain driver is used with a pull-up resistor to 5 V to provide the logic '1' input, and  $V_{CC1}$  is set to 3.3 V on the SX-A device, the input signal may be pulled down by the SX-A input.

Each I/O module has an available power-up resistor of approximately 50 k $\Omega$  that can configure the I/O in a known state during power-up. For nominal pull-up and pull-down resistor values, refer to Table 1-4 on page 1-8 of the application note *Actel eX, SX-A, and RTSX-S I/Os*. Just slightly before  $V_{CCA}$  reaches 2.5 V, the resistors are disabled, so the I/Os will be controlled by user logic. See Table 1-2 on page 1-8 and Table 1-3 on page 1-8 for more information concerning available I/O features.

## JTAG Instructions

Table 1-7 lists the supported instructions with the corresponding IR codes for SX-A devices.

Table 1-8 lists the codes returned after executing the IDCODE instruction for SX-A devices. Note that bit 0 is always '1'. Bits 11-1 are always '02F', which is the Actel manufacturer code.

Table 1-7 • JTAG Instruction Code

Instructions (IR4:IR0)	Binary Code
EXTEST	00000
SAMPLE/PRELOAD	00001
INTEST	00010
USERCODE	00011
IDCODE	00100
HighZ	01110
CLAMP	01111
Diagnostic	10000
BYPASS	11111
Reserved	All others

Table 1-8 • JTAG Instruction Code

Device	Process	Revision	Bits 31-28	Bits 27-12
A54SX08A	0.22 μ	0	8, 9	40B4, 42B4
		1	A, B	40B4, 42B4
A54SX16A	0.22 μ	0	9	40B8, 42B8
		1	B	40B8, 42B8
	0.25 μ	1	B	22B8
A54SX32A	0.2 2μ	0	9	40BD, 42BD
		1	B	40BD, 42BD
	0.25 μ	1	B	22BD
A54SX72A	0.22 μ	0	9	40B2, 42B2
		1	B	40B2, 42B2
	0.25 μ	1	B	22B2



## Theta-JA

Junction-to-ambient thermal resistance ( $\theta_{JA}$ ) is determined under standard conditions specified by JESD-51 series but has little relevance in actual performance of the product in real application. It should be employed with caution but is useful for comparing the thermal performance of one package to another.

A sample calculation to estimate the absolute maximum power dissipation allowed (worst case) for a 329-pin PBGA package at still air is as follows. i.e.:

$$\theta_{JA} = 17.1^{\circ}\text{C/W} \text{ is taken from Table 2-12 on page 2-11}$$

$$T_A = 125^{\circ}\text{C} \text{ is the maximum limit of ambient (from the datasheet)}$$

$$\text{Max. Allowed Power} = \frac{\text{Max Junction Temp} - \text{Max. Ambient Temp}}{\theta_{JA}} = \frac{150^{\circ}\text{C} - 125^{\circ}\text{C}}{17.1^{\circ}\text{C/W}} = 1.46 \text{ W}$$

EQ 2-11

The device's power consumption must be lower than the calculated maximum power dissipation by the package.

The power consumption of a device can be calculated using the Actel power calculator. If the power consumption is higher than the device's maximum allowable power dissipation, then a heat sink can be attached on top of the case or the airflow inside the system must be increased.

## Theta-JC

Junction-to-case thermal resistance ( $\theta_{JC}$ ) measures the ability of a device to dissipate heat from the surface of the chip to the top or bottom surface of the package. It is applicable for packages used with external heat sinks and only applies to situations where all or nearly all of the heat is dissipated through the surface in consideration. If the power consumption is higher than the calculated maximum power dissipation of the package, then a heat sink is required.

## Calculation for Heat Sink

For example, in a design implemented in a FG484 package, the power consumption value using the power calculator is 3.00 W. The user-dependent data  $T_J$  and  $T_A$  are given as follows:

$$T_J = 110^{\circ}\text{C}$$

$$T_A = 70^{\circ}\text{C}$$

From the datasheet:

$$\theta_{JA} = 18.0^{\circ}\text{C/W}$$

$$\theta_{JC} = 3.2^{\circ}\text{C/W}$$

$$P = \frac{\text{Max Junction Temp} - \text{Max. Ambient Temp}}{\theta_{JA}} = \frac{110^{\circ}\text{C} - 70^{\circ}\text{C}}{18.0^{\circ}\text{C/W}} = 2.22 \text{ W}$$

EQ 2-12

The 2.22 W power is less than then required 3.00 W; therefore, the design requires a heat sink or the airflow where the device is mounted should be increased. The design's junction-to-air thermal resistance requirement can be estimated by:

$$\theta_{JA} = \frac{\text{Max Junction Temp} - \text{Max. Ambient Temp}}{P} = \frac{110^{\circ}\text{C} - 70^{\circ}\text{C}}{3.00 \text{ W}} = 13.33^{\circ}\text{C/W}$$

EQ 2-13

To determine the heat sink's thermal performance, use the following equation:

$$\theta_{JA(TOTAL)} = \theta_{JC} + \theta_{CS} + \theta_{SA}$$

EQ 2-14

where:

$$\theta_{CS} = 0.37^{\circ}C/W$$

= thermal resistance of the interface material between the case and the heat sink, usually provided by the thermal interface manufacturer

$$\theta_{SA} = \text{thermal resistance of the heat sink in } ^{\circ}C/W$$

$$\theta_{SA} = \theta_{JA(TOTAL)} - \theta_{JC} - \theta_{CS}$$

EQ 2-15

$$\theta_{SA} = 13.33^{\circ}C/W - 3.20^{\circ}C/W - 0.37^{\circ}C/W$$

$$\theta_{SA} = 9.76^{\circ}C/W$$

A heat sink with a thermal resistance of  $9.76^{\circ}C/W$  or better should be used. Thermal resistance of heat sinks is a function of airflow. The heat sink performance can be significantly improved with the presence of airflow.

Carefully estimating thermal resistance is important in the long-term reliability of an Actel FPGA. Design engineers should always correlate the power consumption of the device with the maximum allowable power dissipation of the package selected for that device, using the provided thermal resistance data.

Note: The values may vary depending on the application.

Table 2-16 • A54SX08A Timing Characteristics  
(Worst-Case Commercial Conditions  $V_{CCA} = 2.25\text{ V}$ ,  $V_{CCI} = 3.0\text{ V}$ ,  $T_J = 70^\circ\text{C}$ )

Parameter	Description	-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Dedicated (Hardwired) Array Clock Networks</b>										
$t_{HCKH}$	Input Low to High (Pad to R-cell Input)		1.3		1.5		1.7		2.6	ns
$t_{HCKL}$	Input High to Low (Pad to R-cell Input)		1.1		1.3		1.5		2.2	ns
$t_{HPWH}$	Minimum Pulse Width High	1.6		1.8		2.1		2.9		ns
$t_{HPWL}$	Minimum Pulse Width Low	1.6		1.8		2.1		2.9		ns
$t_{HCKSW}$	Maximum Skew		0.4		0.5		0.5		0.8	ns
$t_{HP}$	Minimum Period	3.2		3.6		4.2		5.8		ns
$f_{HMAX}$	Maximum Frequency		313		278		238		172	MHz
<b>Routed Array Clock Networks</b>										
$t_{RCKH}$	Input Low to High (Light Load) (Pad to R-cell Input)		0.8		0.9		1.1		1.5	ns
$t_{RCKL}$	Input High to Low (Light Load) (Pad to R-cell Input)		1.1		1.2		1.4		2	ns
$t_{RCKH}$	Input Low to High (50% Load) (Pad to R-cell Input)		0.8		0.9		1.1		1.5	ns
$t_{RCKL}$	Input High to Low (50% Load) (Pad to R-cell Input)		1.1		1.2		1.4		2	ns
$t_{RCKH}$	Input Low to High (100% Load) (Pad to R-cell Input)		1.1		1.2		1.4		1.9	ns
$t_{RCKL}$	Input High to Low (100% Load) (Pad to R-cell Input)		1.2		1.3		1.6		2.2	ns
$t_{RPWH}$	Minimum Pulse Width High	1.6		1.8		2.1		2.9		ns
$t_{RPWL}$	Minimum Pulse Width Low	1.6		1.8		2.1		2.9		ns
$t_{RCKSW}$	Maximum Skew (Light Load)		0.7		0.8		0.9		1.3	ns
$t_{RCKSW}$	Maximum Skew (50% Load)		0.7		0.8		0.9		1.3	ns
$t_{RCKSW}$	Maximum Skew (100% Load)		0.8		0.9		1.1		1.5	ns



Table 2-17 • A54SX08A Timing Characteristics  
 (Worst-Case Commercial Conditions  $V_{CCA} = 2.25\text{ V}$ ,  $V_{CCI} = 4.75\text{ V}$ ,  $T_J = 70^\circ\text{C}$ )

Parameter	Description	-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Dedicated (Hardwired) Array Clock Networks</b>										
$t_{HCKH}$	Input Low to High (Pad to R-cell Input)		1.2		1.3		1.5		2.3	ns
$t_{HCKL}$	Input High to Low (Pad to R-cell Input)		1.0		1.2		1.4		2.0	ns
$t_{HPWH}$	Minimum Pulse Width High	1.6		1.8		2.1		2.9		ns
$t_{HPWL}$	Minimum Pulse Width Low	1.6		1.8		2.1		2.9		ns
$t_{HCKSW}$	Maximum Skew		0.4		0.4		0.5		0.8	ns
$t_{HP}$	Minimum Period	3.2		3.6		4.2		5.8		ns
$f_{HMAX}$	Maximum Frequency		313		278		238		172	MHz
<b>Routed Array Clock Networks</b>										
$t_{RCKH}$	Input Low to High (Light Load) (Pad to R-cell Input)		0.9		1.0		1.2		1.7	ns
$t_{RCKL}$	Input High to Low (Light Load) (Pad to R-cell Input)		1.5		1.7		2.0		2.7	ns
$t_{RCKH}$	Input Low to High (50% Load) (Pad to R-cell Input)		0.9		1.0		1.2		1.7	ns
$t_{RCKL}$	Input High to Low (50% Load) (Pad to R-cell Input)		1.5		1.7		2.0		2.7	ns
$t_{RCKH}$	Input Low to High (100% Load) (Pad to R-cell Input)		1.1		1.3		1.5		2.1	ns
$t_{RCKL}$	Input High to Low (100% Load) (Pad to R-cell Input)		1.6		1.8		2.1		2.9	ns
$t_{RPWH}$	Minimum Pulse Width High	1.6		1.8		2.1		2.9		ns
$t_{RPWL}$	Minimum Pulse Width Low	1.6		1.8		2.1		2.9		ns
$t_{RCKSW}$	Maximum Skew (Light Load)		0.8		0.9		1.1		1.5	ns
$t_{RCKSW}$	Maximum Skew (50% Load)		0.8		1.0		1.1		1.5	ns
$t_{RCKSW}$	Maximum Skew (100% Load)		0.9		1.0		1.2		1.7	ns

Table 2-25 • A54SX16A Timing Characteristics  
(Worst-Case Commercial Conditions  $V_{CCA} = 2.25\text{ V}$ ,  $V_{CCI} = 2.25\text{ V}$ ,  $T_J = 70^\circ\text{C}$ )

Parameter	Description	-3 Speed <sup>1</sup>		-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>2.5 V LVCMOS Output Module Timing<sup>2, 3</sup></b>												
$t_{DLH}$	Data-to-Pad Low to High	3.4		3.9		4.5		5.2		7.3		ns
$t_{DHL}$	Data-to-Pad High to Low	2.6		3.0		3.3		3.9		5.5		ns
$t_{DHLS}$	Data-to-Pad High to Low—low slew	11.6		13.4		15.2		17.9		25.0		ns
$t_{ENZL}$	Enable-to-Pad, Z to L	2.4		2.8		3.2		3.7		5.2		ns
$t_{ENZLS}$	Data-to-Pad, Z to L—low slew	11.8		13.7		15.5		18.2		25.5		ns
$t_{ENZH}$	Enable-to-Pad, Z to H	3.4		3.9		4.5		5.2		7.3		ns
$t_{ENLZ}$	Enable-to-Pad, L to Z	2.1		2.5		2.8		3.3		4.7		ns
$t_{ENHZ}$	Enable-to-Pad, H to Z	2.6		3.0		3.3		3.9		5.5		ns
$d_{TLH}^4$	Delta Low to High	0.031		0.037		0.043		0.051		0.071		ns/pF
$d_{THL}^4$	Delta High to Low	0.017		0.017		0.023		0.023		0.037		ns/pF
$d_{THLS}^4$	Delta High to Low—low slew	0.057		0.06		0.071		0.086		0.117		ns/pF

**Note:**

- All -3 speed grades have been discontinued.
- Delays based on 35 pF loading.
- The equivalent IO Attribute settings for 2.5 V LVCMOS is 2.5 V LVTTTL in the software.
- To obtain the slew rate, substitute the appropriate Delta value, load capacitance, and the  $V_{CCI}$  value into the following equation:  

$$\text{Slew Rate [V/ns]} = (0.1 * V_{CCI} - 0.9 * V_{CCI}) / (C_{load} * d_{T[HLH|HL|HLS]})$$
 where  $C_{load}$  is the load capacitance driven by the I/O in pF  
 $d_{T[HLH|HL|HLS]}$  is the worst case delta value from the datasheet in ns/pF.

Table 2-29 • A54SX32A Timing Characteristics  
(Worst-Case Commercial Conditions  $V_{CCA} = 2.25\text{ V}$ ,  $V_{CCI} = 2.25\text{ V}$ ,  $T_J = 70^\circ\text{C}$ )

Parameter	Description	-3 Speed*		-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>Dedicated (Hardwired) Array Clock Networks</b>												
$t_{HCKH}$	Input Low to High (Pad to R-cell Input)		1.7		2.0		2.2		2.6		4.0	ns
$t_{HCKL}$	Input High to Low (Pad to R-cell Input)		1.7		2.0		2.2		2.6		4.0	ns
$t_{HPWH}$	Minimum Pulse Width High	1.4		1.6		1.8		2.1		2.9		ns
$t_{HPWL}$	Minimum Pulse Width Low	1.4		1.6		1.8		2.1		2.9		ns
$t_{HCKSW}$	Maximum Skew		0.6		0.6		0.7		0.8		1.3	ns
$t_{HP}$	Minimum Period	2.8		3.2		3.6		4.2		5.8		ns
$f_{HMAX}$	Maximum Frequency		357		313		278		238		172	MHz
<b>Routed Array Clock Networks</b>												
$t_{RCKH}$	Input Low to High (Light Load) (Pad to R-cell Input)		2.2		2.5		2.9		3.4		4.7	ns
$t_{RCKL}$	Input High to Low (Light Load) (Pad to R-cell Input)		2.1		2.4		2.7		3.2		4.4	ns
$t_{RCKH}$	Input Low to High (50% Load) (Pad to R-cell Input)		2.4		2.7		3.1		3.6		5.1	ns
$t_{RCKL}$	Input High to Low (50% Load) (Pad to R-cell Input)		2.2		2.5		2.8		3.3		4.6	ns
$t_{RCKH}$	Input Low to High (100% Load) (Pad to R-cell Input)		2.5		2.9		3.2		3.8		5.3	ns
$t_{RCKL}$	Input High to Low (100% Load) (Pad to R-cell Input)		2.4		2.7		3.1		3.6		5.0	ns
$t_{RPWH}$	Minimum Pulse Width High	1.4		1.6		1.8		2.1		2.9		ns
$t_{RPWL}$	Minimum Pulse Width Low	1.4		1.6		1.8		2.1		2.9		ns
$t_{RCKSW}$	Maximum Skew (Light Load)		1.0		1.1		1.3		1.5		2.1	ns
$t_{RCKSW}$	Maximum Skew (50% Load)		0.9		1.0		1.2		1.4		1.9	ns
$t_{RCKSW}$	Maximum Skew (100% Load)		0.9		1.0		1.2		1.4		1.9	ns

**Note:** \*All -3 speed grades have been discontinued.

## SX-A Family FPGAs

Table 2-35 • A54SX72A Timing Characteristics  
(Worst-Case Commercial Conditions,  $V_{CCA} = 2.25\text{ V}$ ,  $V_{CCI} = 3.0\text{ V}$ ,  $T_J = 70^\circ\text{C}$ )

Parameter	Description	-3 Speed <sup>1</sup>		-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
<b>C-Cell Propagation Delays<sup>2</sup></b>												
$t_{PD}$	Internal Array Module	1.0		1.1		1.3		1.5		2.0		ns
<b>Predicted Routing Delays<sup>3</sup></b>												
$t_{DC}$	FO = 1 Routing Delay, Direct Connect	0.1		0.1		0.1		0.1		0.1		ns
$t_{FC}$	FO = 1 Routing Delay, Fast Connect	0.3		0.3		0.3		0.4		0.6		ns
$t_{RD1}$	FO = 1 Routing Delay	0.3		0.3		0.4		0.5		0.7		ns
$t_{RD2}$	FO = 2 Routing Delay	0.4		0.5		0.6		0.7		1		ns
$t_{RD3}$	FO = 3 Routing Delay	0.5		0.7		0.8		0.9		1.3		ns
$t_{RD4}$	FO = 4 Routing Delay	0.7		0.9		1		1.1		1.5		ns
$t_{RD8}$	FO = 8 Routing Delay	1.2		1.5		1.7		2.1		2.9		ns
$t_{RD12}$	FO = 12 Routing Delay	1.7		2.2		2.5		3		4.2		ns
<b>R-Cell Timing</b>												
$t_{RCO}$	Sequential Clock-to-Q	0.7		0.8		0.9		1.1		1.5		ns
$t_{CLR}$	Asynchronous Clear-to-Q	0.6		0.7		0.7		0.9		1.2		ns
$t_{PRESET}$	Asynchronous Preset-to-Q	0.7		0.8		0.8		1.0		1.4		ns
$t_{SUD}$	Flip-Flop Data Input Set-Up	0.7		0.8		0.9		1.0		1.4		ns
$t_{HD}$	Flip-Flop Data Input Hold	0.0		0.0		0.0		0.0		0.0		ns
$t_{WASYN}$	Asynchronous Pulse Width	1.3		1.5		1.7		2.0		2.8		ns
$t_{REASYN}$	Asynchronous Recovery Time	0.3		0.4		0.4		0.5		0.7		ns
$t_{HASYN}$	Asynchronous Hold Time	0.3		0.3		0.3		0.4		0.6		ns
$t_{MPW}$	Clock Minimum Pulse Width	1.5		1.7		2.0		2.3		3.2		ns
<b>Input Module Propagation Delays</b>												
$t_{INYH}$	Input Data Pad to Y High 2.5 V LVCMOS	0.6		0.7		0.8		0.9		1.3		ns
$t_{INYL}$	Input Data Pad to Y Low 2.5 V LVCMOS	0.8		1.0		1.1		1.3		1.7		ns
$t_{INYH}$	Input Data Pad to Y High 3.3 V PCI	0.6		0.7		0.7		0.9		1.2		ns
$t_{INYL}$	Input Data Pad to Y Low 3.3 V PCI	0.7		0.8		0.9		1.0		1.4		ns
$t_{INYH}$	Input Data Pad to Y High 3.3 V LVTTTL	0.7		0.7		0.8		1.0		1.4		ns
$t_{INYL}$	Input Data Pad to Y Low 3.3 V LVTTTL	1.0		1.2		1.3		1.5		2.1		ns

### Notes:

1. All -3 speed grades have been discontinued.
2. For dual-module macros, use  $t_{PD} + t_{RD1} + t_{PDn}$ ,  $t_{RCO} + t_{RD1} + t_{PDn}$ , or  $t_{PD1} + t_{RD1} + t_{SUD}$ , whichever is appropriate.
3. Routing delays are for typical designs across worst-case operating conditions. These parameters should be used for estimating device performance. Post-route timing analysis or simulation is required to determine actual performance.

Table 2-38 • A54SX72A Timing Characteristics (Continued)  
 (Worst-Case Commercial Conditions  $V_{CCA} = 2.25\text{ V}$ ,  $V_{CCI} = 4.75\text{ V}$ ,  $T_J = 70^\circ\text{C}$ )

Parameter	Description	-3 Speed*		-2 Speed		-1 Speed		Std. Speed		-F Speed		Units
		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	
$t_{QCKH}$	Input Low to High (100% Load) (Pad to R-cell Input)		1.6		1.8		2.1		2.4		3.4	ns
$t_{QCHKL}$	Input High to Low (100% Load) (Pad to R-cell Input)		1.6		1.9		2.1		2.5		3.5	ns
$t_{QPWH}$	Minimum Pulse Width High	1.5		1.7		2.0		2.3		3.2		ns
$t_{QPWL}$	Minimum Pulse Width Low	1.5		1.7		2.0		2.3		3.2		ns
$t_{QCKSW}$	Maximum Skew (Light Load)		0.2		0.3		0.3		0.3		0.5	ns
$t_{QCKSW}$	Maximum Skew (50% Load)		0.4		0.5		0.5		0.6		0.9	ns
$t_{QCKSW}$	Maximum Skew (100% Load)		0.4		0.5		0.5		0.6		0.9	ns

**Note:** \*All -3 speed grades have been discontinued.

## 100-Pin TQFP

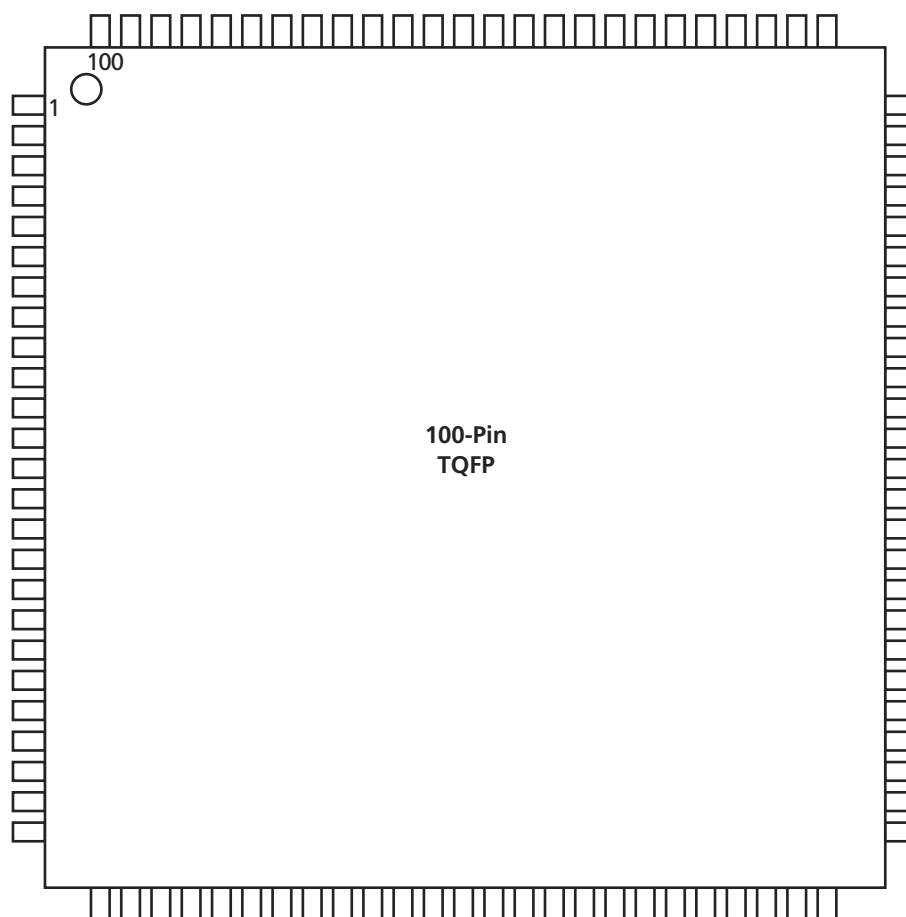


Figure 3-2 • 100-Pin TQFP

### Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.actel.com/products/rescenter/package/index.html>.

# 144-Pin TQFP

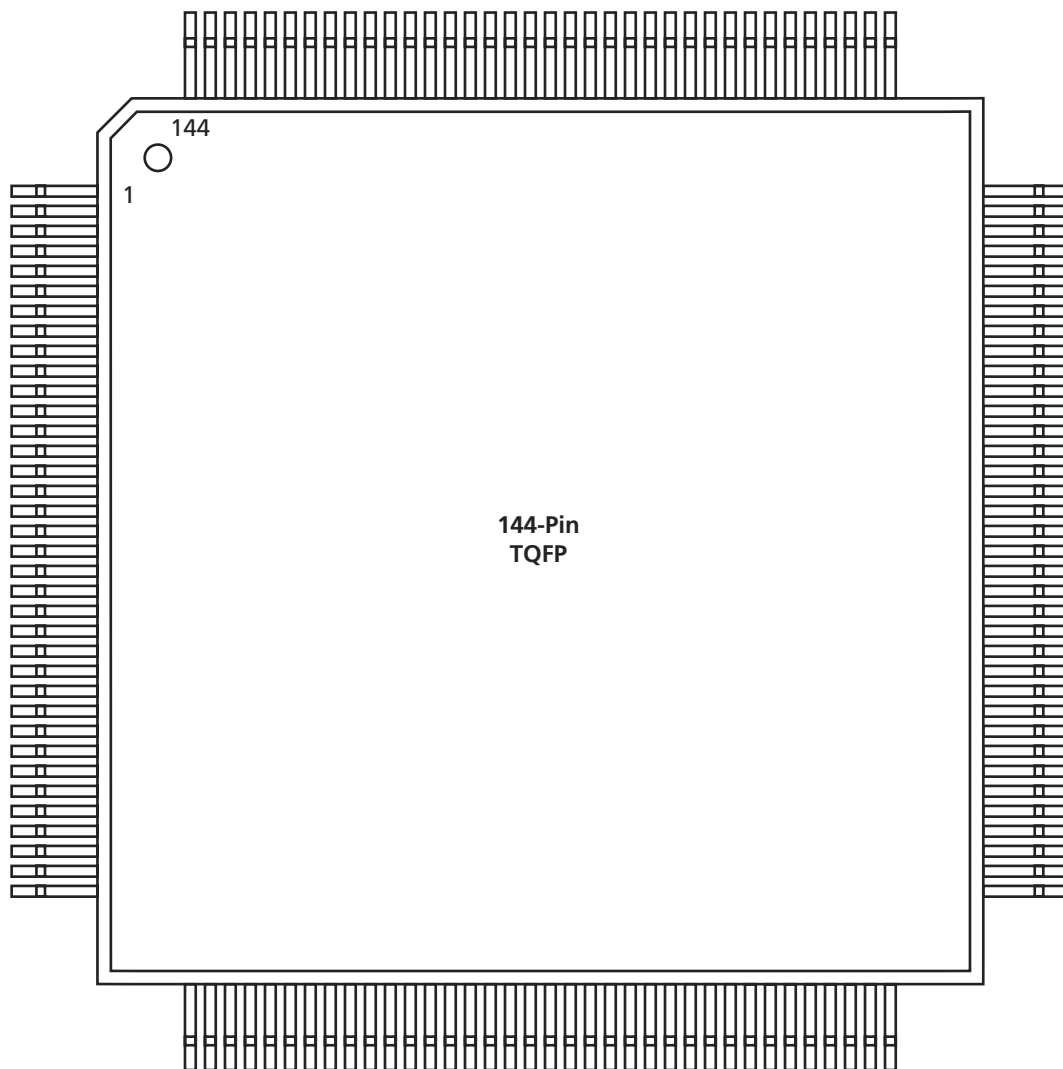


Figure 3-3 • 144-Pin TQFP (Top View)

### Note

For Package Manufacturing and Environmental information, visit Resource center at <http://www.actel.com/products/rescenter/package/index.html>.

144-Pin TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
1	GND	GND	GND
2	TDI, I/O	TDI, I/O	TDI, I/O
3	I/O	I/O	I/O
4	I/O	I/O	I/O
5	I/O	I/O	I/O
6	I/O	I/O	I/O
7	I/O	I/O	I/O
8	I/O	I/O	I/O
9	TMS	TMS	TMS
10	V <sub>CCI</sub>	V <sub>CCI</sub>	V <sub>CCI</sub>
11	GND	GND	GND
12	I/O	I/O	I/O
13	I/O	I/O	I/O
14	I/O	I/O	I/O
15	I/O	I/O	I/O
16	I/O	I/O	I/O
17	I/O	I/O	I/O
18	I/O	I/O	I/O
19	NC	NC	NC
20	V <sub>CCA</sub>	V <sub>CCA</sub>	V <sub>CCA</sub>
21	I/O	I/O	I/O
22	TRST, I/O	TRST, I/O	TRST, I/O
23	I/O	I/O	I/O
24	I/O	I/O	I/O
25	I/O	I/O	I/O
26	I/O	I/O	I/O
27	I/O	I/O	I/O
28	GND	GND	GND
29	V <sub>CCI</sub>	V <sub>CCI</sub>	V <sub>CCI</sub>
30	V <sub>CCA</sub>	V <sub>CCA</sub>	V <sub>CCA</sub>
31	I/O	I/O	I/O
32	I/O	I/O	I/O
33	I/O	I/O	I/O
34	I/O	I/O	I/O
35	I/O	I/O	I/O
36	GND	GND	GND
37	I/O	I/O	I/O

144-Pin TQFP			
Pin Number	A54SX08A Function	A54SX16A Function	A54SX32A Function
38	I/O	I/O	I/O
39	I/O	I/O	I/O
40	I/O	I/O	I/O
41	I/O	I/O	I/O
42	I/O	I/O	I/O
43	I/O	I/O	I/O
44	V <sub>CCI</sub>	V <sub>CCI</sub>	V <sub>CCI</sub>
45	I/O	I/O	I/O
46	I/O	I/O	I/O
47	I/O	I/O	I/O
48	I/O	I/O	I/O
49	I/O	I/O	I/O
50	I/O	I/O	I/O
51	I/O	I/O	I/O
52	I/O	I/O	I/O
53	I/O	I/O	I/O
54	PRB, I/O	PRB, I/O	PRB, I/O
55	I/O	I/O	I/O
56	V <sub>CCA</sub>	V <sub>CCA</sub>	V <sub>CCA</sub>
57	GND	GND	GND
58	NC	NC	NC
59	I/O	I/O	I/O
60	HCLK	HCLK	HCLK
61	I/O	I/O	I/O
62	I/O	I/O	I/O
63	I/O	I/O	I/O
64	I/O	I/O	I/O
65	I/O	I/O	I/O
66	I/O	I/O	I/O
67	I/O	I/O	I/O
68	V <sub>CCI</sub>	V <sub>CCI</sub>	V <sub>CCI</sub>
69	I/O	I/O	I/O
70	I/O	I/O	I/O
71	TDO, I/O	TDO, I/O	TDO, I/O
72	I/O	I/O	I/O
73	GND	GND	GND
74	I/O	I/O	I/O



176-Pin TQFP	
Pin Number	A54SX32A Function
1	GND
2	TDI, I/O
3	I/O
4	I/O
5	I/O
6	I/O
7	I/O
8	I/O
9	I/O
10	TMS
11	V <sub>CCI</sub>
12	I/O
13	I/O
14	I/O
15	I/O
16	I/O
17	I/O
18	I/O
19	I/O
20	I/O
21	GND
22	V <sub>CCA</sub>
23	GND
24	I/O
25	TRST, I/O
26	I/O
27	I/O
28	I/O
29	I/O
30	I/O
31	I/O
32	V <sub>CCI</sub>
33	V <sub>CCA</sub>
34	I/O
35	I/O
36	I/O

176-Pin TQFP	
Pin Number	A54SX32A Function
37	I/O
38	I/O
39	I/O
40	I/O
41	I/O
42	I/O
43	I/O
44	GND
45	I/O
46	I/O
47	I/O
48	I/O
49	I/O
50	I/O
51	I/O
52	V <sub>CCI</sub>
53	I/O
54	I/O
55	I/O
56	I/O
57	I/O
58	I/O
59	I/O
60	I/O
61	I/O
62	I/O
63	I/O
64	PRB, I/O
65	GND
66	V <sub>CCA</sub>
67	NC
68	I/O
69	HCLK
70	I/O
71	I/O
72	I/O

176-Pin TQFP	
Pin Number	A54SX32A Function
73	I/O
74	I/O
75	I/O
76	I/O
77	I/O
78	I/O
79	I/O
80	I/O
81	I/O
82	V <sub>CCI</sub>
83	I/O
84	I/O
85	I/O
86	I/O
87	TDO, I/O
88	I/O
89	GND
90	I/O
91	I/O
92	I/O
93	I/O
94	I/O
95	I/O
96	I/O
97	I/O
98	V <sub>CCA</sub>
99	V <sub>CCI</sub>
100	I/O
101	I/O
102	I/O
103	I/O
104	I/O
105	I/O
106	I/O
107	I/O
108	GND

176-Pin TQFP	
Pin Number	A54SX32A Function
109	V <sub>CCA</sub>
110	GND
111	I/O
112	I/O
113	I/O
114	I/O
115	I/O
116	I/O
117	I/O
118	I/O
119	I/O
120	I/O
121	I/O
122	V <sub>CCA</sub>
123	GND
124	V <sub>CCI</sub>
125	I/O
126	I/O
127	I/O
128	I/O
129	I/O
130	I/O
131	I/O
132	I/O
133	GND
134	I/O
135	I/O
136	I/O
137	I/O
138	I/O
139	I/O
140	V <sub>CCI</sub>
141	I/O
142	I/O
143	I/O
144	I/O

176-Pin TQFP	
Pin Number	A54SX32A Function
145	I/O
146	I/O
147	I/O
148	I/O
149	I/O
150	I/O
151	I/O
152	CLKA
153	CLKB
154	NC
155	GND
156	V <sub>CCA</sub>
157	PRA, I/O
158	I/O
159	I/O
160	I/O
161	I/O
162	I/O
163	I/O
164	I/O
165	I/O
166	I/O
167	I/O
168	I/O
169	V <sub>CCI</sub>
170	I/O
171	I/O
172	I/O
173	I/O
174	I/O
175	I/O
176	TCK, I/O

329-Pin PBGA	
Pin Number	A54SX32A Function
D11	V <sub>CCA</sub>
D12	NC
D13	I/O
D14	I/O
D15	I/O
D16	I/O
D17	I/O
D18	I/O
D19	I/O
D20	I/O
D21	I/O
D22	I/O
D23	I/O
E1	V <sub>CCI</sub>
E2	I/O
E3	I/O
E4	I/O
E20	I/O
E21	I/O
E22	I/O
E23	I/O
F1	I/O
F2	TMS
F3	I/O
F4	I/O
F20	I/O
F21	I/O
F22	I/O
F23	I/O
G1	I/O
G2	I/O
G3	I/O
G4	I/O
G20	I/O
G21	I/O
G22	I/O
G23	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
H1	I/O
H2	I/O
H3	I/O
H4	I/O
H20	V <sub>CCA</sub>
H21	I/O
H22	I/O
H23	I/O
J1	NC
J2	I/O
J3	I/O
J4	I/O
J20	I/O
J21	I/O
J22	I/O
J23	I/O
K1	I/O
K2	I/O
K3	I/O
K4	I/O
K10	GND
K11	GND
K12	GND
K13	GND
K14	GND
K20	I/O
K21	I/O
K22	I/O
K23	I/O
L1	I/O
L2	I/O
L3	I/O
L4	NC
L10	GND
L11	GND
L12	GND
L13	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
L14	GND
L20	NC
L21	I/O
L22	I/O
L23	NC
M1	I/O
M2	I/O
M3	I/O
M4	V <sub>CCA</sub>
M10	GND
M11	GND
M12	GND
M13	GND
M14	GND
M20	V <sub>CCA</sub>
M21	I/O
M22	I/O
M23	V <sub>CCI</sub>
N1	I/O
N2	TRST, I/O
N3	I/O
N4	I/O
N10	GND
N11	GND
N12	GND
N13	GND
N14	GND
N20	NC
N21	I/O
N22	I/O
N23	I/O
P1	I/O
P2	I/O
P3	I/O
P4	I/O
P10	GND
P11	GND

329-Pin PBGA	
Pin Number	A54SX32A Function
P12	GND
P13	GND
P14	GND
P20	I/O
P21	I/O
P22	I/O
P23	I/O
R1	I/O
R2	I/O
R3	I/O
R4	I/O
R20	I/O
R21	I/O
R22	I/O
R23	I/O
T1	I/O
T2	I/O
T3	I/O
T4	I/O
T20	I/O
T21	I/O
T22	I/O
T23	I/O
U1	I/O
U2	I/O
U3	V <sub>CCA</sub>
U4	I/O
U20	I/O
U21	V <sub>CCA</sub>
U22	I/O
U23	I/O
V1	V <sub>CCI</sub>
V2	I/O
V3	I/O
V4	I/O
V20	I/O
V21	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
A1	NC*	NC
A2	NC*	NC
A3	NC*	I/O
A4	NC*	I/O
A5	NC*	I/O
A6	I/O	I/O
A7	I/O	I/O
A8	I/O	I/O
A9	I/O	I/O
A10	I/O	I/O
A11	NC*	I/O
A12	NC*	I/O
A13	I/O	I/O
A14	NC*	NC
A15	NC*	I/O
A16	NC*	I/O
A17	I/O	I/O
A18	I/O	I/O
A19	I/O	I/O
A20	I/O	I/O
A21	NC*	I/O
A22	NC*	I/O
A23	NC*	I/O
A24	NC*	I/O
A25	NC*	NC
A26	NC*	NC
AA1	NC*	I/O
AA2	NC*	I/O
AA3	V <sub>CCA</sub>	V <sub>CCA</sub>
AA4	I/O	I/O
AA5	I/O	I/O
AA22	I/O	I/O
AA23	I/O	I/O
AA24	I/O	I/O
AA25	NC*	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AA26	NC*	I/O
AB1	NC*	NC
AB2	V <sub>CCI</sub>	V <sub>CCI</sub>
AB3	I/O	I/O
AB4	I/O	I/O
AB5	NC*	I/O
AB6	I/O	I/O
AB7	I/O	I/O
AB8	I/O	I/O
AB9	I/O	I/O
AB10	I/O	I/O
AB11	I/O	I/O
AB12	PRB, I/O	PRB, I/O
AB13	V <sub>CCA</sub>	V <sub>CCA</sub>
AB14	I/O	I/O
AB15	I/O	I/O
AB16	I/O	I/O
AB17	I/O	I/O
AB18	I/O	I/O
AB19	I/O	I/O
AB20	TDO, I/O	TDO, I/O
AB21	GND	GND
AB22	NC*	I/O
AB23	I/O	I/O
AB24	I/O	I/O
AB25	NC*	I/O
AB26	NC*	I/O
AC1	I/O	I/O
AC2	I/O	I/O
AC3	I/O	I/O
AC4	NC*	I/O
AC5	V <sub>CCI</sub>	V <sub>CCI</sub>
AC6	I/O	I/O
AC7	V <sub>CCI</sub>	V <sub>CCI</sub>
AC8	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
AC9	I/O	I/O
AC10	I/O	I/O
AC11	I/O	I/O
AC12	I/O	QCLKA
AC13	I/O	I/O
AC14	I/O	I/O
AC15	I/O	I/O
AC16	I/O	I/O
AC17	I/O	I/O
AC18	I/O	I/O
AC19	I/O	I/O
AC20	V <sub>CCI</sub>	V <sub>CCI</sub>
AC21	I/O	I/O
AC22	I/O	I/O
AC23	NC*	I/O
AC24	I/O	I/O
AC25	NC*	I/O
AC26	NC*	I/O
AD1	I/O	I/O
AD2	I/O	I/O
AD3	GND	GND
AD4	I/O	I/O
AD5	I/O	I/O
AD6	I/O	I/O
AD7	I/O	I/O
AD8	I/O	I/O
AD9	V <sub>CCI</sub>	V <sub>CCI</sub>
AD10	I/O	I/O
AD11	I/O	I/O
AD12	I/O	I/O
AD13	V <sub>CCI</sub>	V <sub>CCI</sub>
AD14	I/O	I/O
AD15	I/O	I/O
AD16	I/O	I/O
AD17	V <sub>CCI</sub>	V <sub>CCI</sub>

**Note:** \*These pins must be left floating on the A54SX32A device.

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
K10	GND	GND
K11	GND	GND
K12	GND	GND
K13	GND	GND
K14	GND	GND
K15	GND	GND
K16	GND	GND
K17	GND	GND
K22	I/O	I/O
K23	I/O	I/O
K24	NC*	NC
K25	NC*	I/O
K26	NC*	I/O
L1	NC*	I/O
L2	NC*	I/O
L3	I/O	I/O
L4	I/O	I/O
L5	I/O	I/O
L10	GND	GND
L11	GND	GND
L12	GND	GND
L13	GND	GND
L14	GND	GND
L15	GND	GND
L16	GND	GND
L17	GND	GND
L22	I/O	I/O
L23	I/O	I/O
L24	I/O	I/O
L25	I/O	I/O
L26	I/O	I/O
M1	NC*	NC
M2	I/O	I/O
M3	I/O	I/O
M4	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
M5	I/O	I/O
M10	GND	GND
M11	GND	GND
M12	GND	GND
M13	GND	GND
M14	GND	GND
M15	GND	GND
M16	GND	GND
M17	GND	GND
M22	I/O	I/O
M23	I/O	I/O
M24	I/O	I/O
M25	NC*	I/O
M26	NC*	I/O
N1	I/O	I/O
N2	V <sub>CCI</sub>	V <sub>CCI</sub>
N3	I/O	I/O
N4	I/O	I/O
N5	I/O	I/O
N10	GND	GND
N11	GND	GND
N12	GND	GND
N13	GND	GND
N14	GND	GND
N15	GND	GND
N16	GND	GND
N17	GND	GND
N22	V <sub>CCA</sub>	V <sub>CCA</sub>
N23	I/O	I/O
N24	I/O	I/O
N25	I/O	I/O
N26	NC*	NC
P1	NC*	I/O
P2	NC*	I/O
P3	I/O	I/O

484-Pin FBGA		
Pin Number	A54SX32A Function	A54SX72A Function
P4	I/O	I/O
P5	V <sub>CCA</sub>	V <sub>CCA</sub>
P10	GND	GND
P11	GND	GND
P12	GND	GND
P13	GND	GND
P14	GND	GND
P15	GND	GND
P16	GND	GND
P17	GND	GND
P22	I/O	I/O
P23	I/O	I/O
P24	V <sub>CCI</sub>	V <sub>CCI</sub>
P25	I/O	I/O
P26	I/O	I/O
R1	NC*	I/O
R2	NC*	I/O
R3	I/O	I/O
R4	I/O	I/O
R5	TRST, I/O	TRST, I/O
R10	GND	GND
R11	GND	GND
R12	GND	GND
R13	GND	GND
R14	GND	GND
R15	GND	GND
R16	GND	GND
R17	GND	GND
R22	I/O	I/O
R23	I/O	I/O
R24	I/O	I/O
R25	NC*	I/O
R26	NC*	I/O
T1	NC*	I/O
T2	NC*	I/O

**Note:** \*These pins must be left floating on the A54SX32A device.